

DDR5 DIMM Socket



Doubling DDR4 bandwidth and density with improved performance and power efficiency, DDR5 DIMM socket delivers 6.4 Gbps speed with smaller socket footprint and lower seating plane for greater PCB and vertical space savings

Features and Advantages

Lead-in Chamfer

Facilitates the smooth insertion of the memory module into the socket

Metal-insert

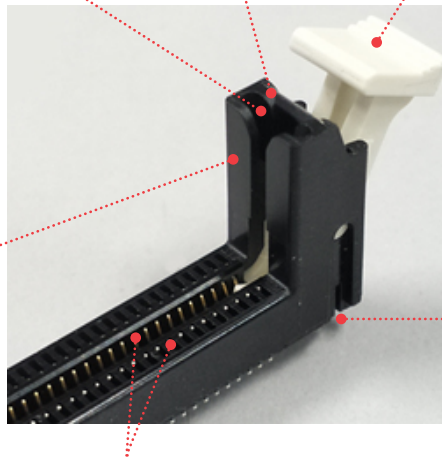
Supports rigorous latch operations and while strengthening the latch tower

Robust, ergonomically designed latch

Improves rip-out force and vibration resistance during latching and release of module card

Halogen-free, high-temperature Nylon housing

Supports high reflow temperatures while providing environmental sustainability



Vibration and shock-resistant solder tab (hidden from view)

Offers optimal performance and robust PCB retention during rugged operations

Anti-stubbing Contacts

Enables robust mating contact and electrical reliability

Applications

Data Centers

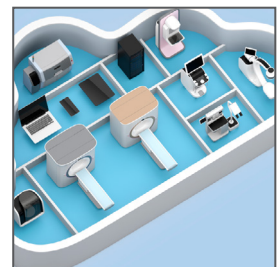
- Big data, real-time analytics
- AI technologies and Machine Learning (a sub-branch of Artificial Intelligence)
- Cloud technologies, IoT
- Blockchain wallet
- Virtualization and AR/VR/MR solutions



Big data systems



Connected security and real-time surveillance systems



Medical information systems

Industrial

- Connected security and real-time surveillance systems (for safe cities, airports, railway stations, ports, key installations, infrastructure and buildings)
- Video surveillance servers
- Industrial internet computing systems

Medical

- Integrated medical information systems

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Specifications

REFERENCE INFORMATION

Packaging: Tray
Use With: Memory Module PCB
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes
Glow Wire Compliant: No

ELECTRICAL

Voltage (max.): 29V AC (RMS) / DC
Current (max.): 0.75A per circuit
Low Level Contact Resistance (max.): 10 milliohm
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance (min.): 1 Megohm

MECHANICAL

Module Insertion Force (with Latches): 106.8N
Module Rip-out Force (min.): 91N
Module Unmating Force
(of 1.27mm thick blade from socket): 2.02 kgf
Terminal Retention Force (min.):
3N (contact): 13N (soldertab)
Latch Actuation Force: 35N per latch
Durability (min.): 25 cycles

PHYSICAL

Housing: Halogen-free, high-temperature Nylon
Contact: Copper Alloy
Plating: 0.375/0.76 micron Gold (Au)
Contact Area — Gold (Au)
Solder Tail Area — Tin (Sn)
Underplating — Nickel (Ni)
PCB Thickness: 1.57 to 3.18mm
Operating Temperature: -55 to +85°C

Note: Molex reserves the right to delay or cancel production of the depicted product without additional notice. Please contact your Molex customer service representative for product availability.

www.molex.com/link/ddr5.html

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